

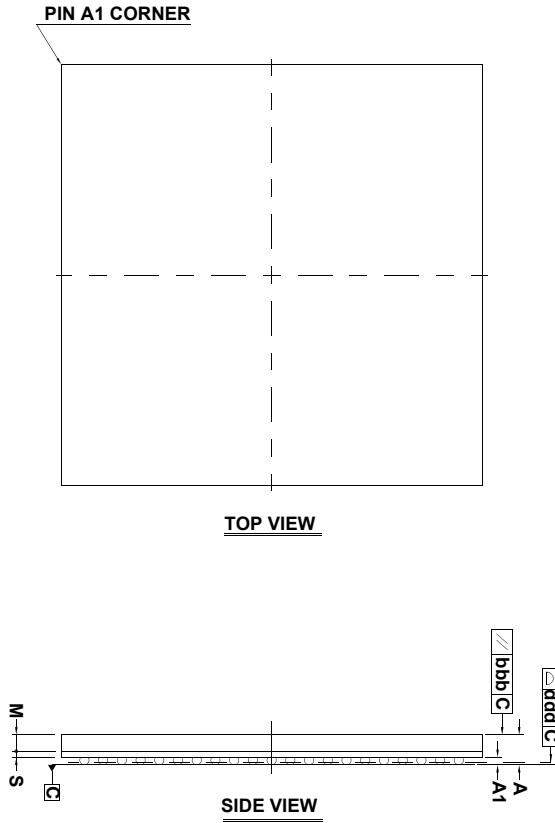
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

V409.18x18

409 LOW PROFILE FINE PITCH PLASTIC BALL GRID ARRAY PACKAGE (LFBGA)

Rev 0, 3/12



	SYMBOL	COMMON DIMENSIONS
Package		LFBGA
Body Size	X	E 18.00
	Y	D 18.00
Ball Pitch		0.800
Total Thickness	A	1.400 MAX
Mold Thickness	M	0.700 Ref.
Substrate Thickness	S	0.260 Ref.
Ball Diameter		0.400
Stand Off	A1	0.270 ~ 0.370
Ball Width	b	0.380 ~ 0.480
Package Edge Tolerance	aaa	0.150
Mold Flatness	bbb	0.200
Coplanarity	ddd	0.120
Ball Offset (Package)	eee	0.150
Ball Offset (Ball)	fff	0.080
Ball Count	n	409
Edge Ball Center to Center	X	E1 16.00
	Y	D1 16.00

